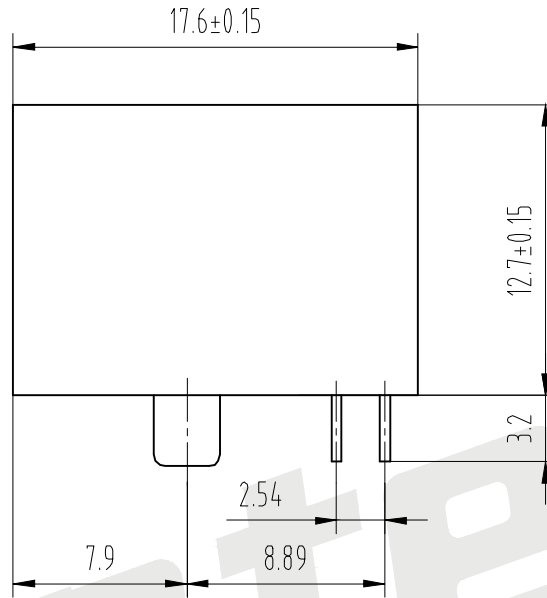
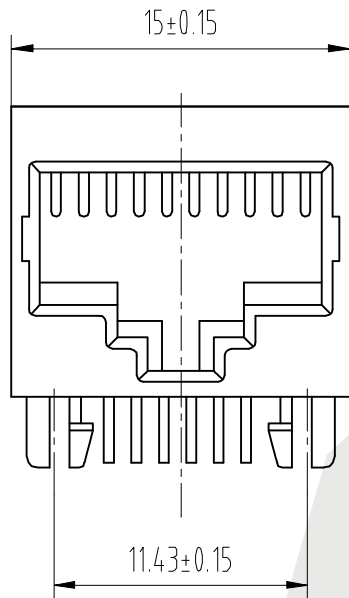


HSF



NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
  2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
  3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
  4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
  2. CURRENT RATING: 1.5AMP
  3. CONTACT RESISTANCE: 30MILLIOHMS MAX
  4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
  5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

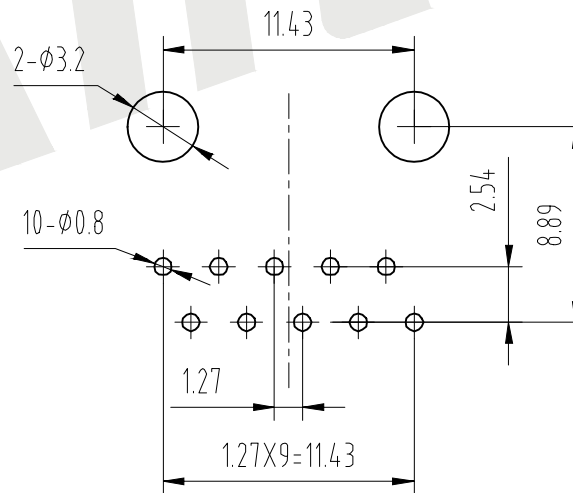
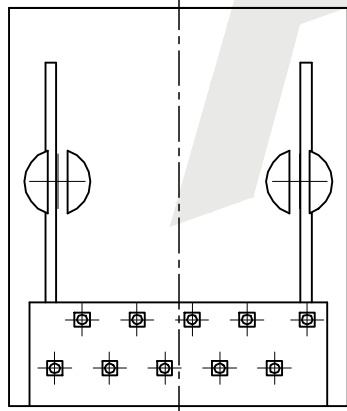
MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
  2. PCB RETENTTON PRB-SOLDER: 1 LB MIN REVRONMENTAL
1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
  2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5621 - 10P - 8C - X - A - X  
 ① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)
- ④ Contact Plating  
 G0: Gold flash  
 G1: 3U" Gold  
 G2: 5U" Gold  
 G3: 10U" Gold  
 G4: 15U" Gold  
 G5: 30U" Gold  
 SN: Tin
- ⑤ Shield  
 A: W/O Shield  
 B: Half Shield  
 C: Shield W/Eml  
 D: Shield W/O Eml
- ⑥ Ports  
 A: 1X1P G: 2X1P  
 B: 1X2P H: 2X2P  
 C: 1X4P I: 2X3P  
 D: 1X5P J: 2X4P  
 E: 1X6P K: 2X6P  
 F: 1X8P L: 2X8P



PC Board Layout  
 Component Side Shown

Unless Otherwise specified tolerance  
 X. ±0.35 X.XX: ±0.20  
 X.X: ±0.25 X.XXX: ±0.15

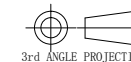
**Antenk** ANTENK ELECTRONICS CO., LTD  
[Http://www.antenk.com](http://www.antenk.com)  
 E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

TITLE: RJ45 Jack side entry, Full Plastic 1X1P

DRAWING NO: ATRJ5621-10P10C-X-A-X

PRODUCT NO: ATRJ5621-10P10C-X-A-X



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		